

Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	3 X 3 X 1.45 (1.6EP)
Lead Count	16
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes with exemption
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	1.89E-02	93.7	937000	49.96		499558
Thermosets	Epoxy resin	Proprietary	6.05E-04	3.0	30000	1.60		15994
Thermosets	Phenol resin	Proprietary	6.05E-04	3.0	30000	1.60		15994
Other inorganic materials	Carbon black	1333-86-4	6.05E-05	0.3	3000	0.16		1599
Subtotal			2.02E-02	100.00	1000000	53.31		533146

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	9.68 E-03	96.20	962000	25.61		256061
Copper & its alloys	Nickel	7440-02-0	3.02 E-04	3.00	30000	0.80		7985
Copper & its alloys	Silicon	7440-21-3	6.54 E-05	0.65	6500	0.17		1730
Copper & its alloys	Magnesium	7439-95-4	1.51 E-05	0.15	1500	0.04		393
Subtotal			1.01 E-02	100.00	1000000	26.62		266176

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	1.90 E-04	100.0	1000000	0.50		5027

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	4.50 E-04	100.0	1000000	1.19		11906

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	5.94 E-05	99.0	990000	0.16		1572
Precious metals	Palladium	7440-05-3	6.00 E-07	1.00	10000	0.002		16
Subtotal			6.00 E-05	100.0	1000000	0.16		1588

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	4.99 E-03	100.0	1000000	13.20		132030

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Thermoset	Resin	Proprietary	5.86 E-04	58	580000	1.55		15500
Other organic materials	Polytetrafluoroethylene	9002-84-0	4.24 E-04	42	420000	1.12		11224
Subtotal			1.01 E-03	100.0	1000000	2.67		26723

Seal Glass

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		PPM
				Percentage (%)	PPM	Percentage (%)	PPM	
Ceramics/Glass	Lead borosilicate glass	65997-17-3	7.74 E-04	87.5	875000	2.05		20478
Ceramics/Glass	Aluminosilicate glass	65997-17-3	1.11 E-04	12.5	125000	0.29		2925
			8.85 E-04			2.34		23403

Package Totals			3.78 E-02			100		1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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